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Details

Product Status	Not For New Designs
Core Processor	HCS12X
Core Size	16-Bit
Speed	80MHz
Connectivity	CANbus, I ² C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	59
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 8x10b, 16x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-QFP
Supplier Device Package	80-QFP (14x14)
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Date	Revision Level	Description
April, 2005	02.07	New Book
May, 2005	02.08	Minor corrections
May, 2005	02.09	removed ESD Machine Model from electrical characteristics added thermal characteristics added more details to run current measurement configurations VDDA supply voltage range 3.15V - 3.6V fot ATD Operating Characteristics I/O Characteristics for all pins except EXTAL, XTAL corrected VREG electrical spec IDD wait max 95mA
May 2005	02.10	Improvements to NVM reliabity spec, added part numbers
July 2005	02.11	Added ROM parts to App.
October 2005	02.12	Single Souce S12XD Fam. Document, New Memory Map Figures,
May 2006	2.13	SPI electricals updated Voltage Regulator electricals updated Added Partnumbers and 1L15Y maskset Updated App. E 6SCI's on 112 pin DT/P512 and 3 SPI's on all D256 parts
June 2006	2.14	Data Sheet covers S12XD/B & A Family Included differnt pull device specification for differnt masksets
July 2006	2.15	Minor Corrections and Improvments
June 2007	2.16	Added 2M42E and 1M84E masksets
July 2007	2.17	Modified Appendix
April 2008	2.18	Better explanation of ATD0/1 for S12XD-Family see page 1305 S12XB256 ATD specification changed see Appendix E.6 added M23S maskset
August 2008	2.19	Corrected XGRAMSIZE of S12XD256 on page 44 Corrected 17.4.2.4 XGATE Memory Map Scheme Corrected 18.4.2.4 XGATE Memory Map Scheme
September 2009	2.20	Corrected Table E-6 , 30K flash memory available for XGATE on B256
October 2009	2.21	Corrected Footnote in Appendix E3 regarding Shared XGATE/CPU area



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Vector Address ¹	XGATE Channel ID ²	Interrupt Source	CCR Mask	Local Enable	
\$FFFE	_	System reset or illegal access reset	None	None	
\$FFFC	_	Clock monitor reset	None	PLLCTL (CME, SCME)	
\$FFFA	_	COP watchdog reset	None	COP rate select	
Vector base + \$F8	—	Unimplemented instruction trap	None	None	
Vector base+ \$F6	_	SWI	None	None	
Vector base+ \$F4	_	XIRQ	X Bit	None	
Vector base+ \$F2	_	ĪRQ	l bit	IRQCR (IRQEN)	
Vector base+ \$F0	\$78	Real time interrupt	l bit	CRGINT (RTIE)	
Vector base+ \$EE	\$77	Enhanced capture timer channel 0	l bit	TIE (COI)	
Vector base + \$EC	\$76	Enhanced capture timer channel 1	l bit	TIE (C1I)	
Vector base+ \$EA	\$75	Enhanced capture timer channel 2	l bit	TIE (C2I)	
Vector base+ \$E8	\$74	Enhanced capture timer channel 3	l bit	TIE (C3I)	
Vector base+ \$E6	\$73	Enhanced capture timer channel 4	l bit	TIE (C4I)	
Vector base+ \$E4	\$72	Enhanced capture timer channel 5	l bit	TIE (C5I)	
Vector base + \$E2	\$71	Enhanced capture timer channel 6	l bit	TIE (C6I)	
Vector base+ \$E0	\$70	Enhanced capture timer channel 7	l bit	TIE (C7I)	
Vector base+ \$DE	\$6F	Enhanced capture timer overflow	l bit	TSRC2 (TOF)	
Vector base+ \$DC	\$6E	Pulse accumulator A overflow	l bit	PACTL (PAOVI)	
Vector base + \$DA	\$6D	Pulse accumulator input edge	l bit	PACTL (PAI)	
Vector base + \$D8	\$6C	SPI0	l bit	SPI0CR1 (SPIE, SPTIE)	
Vector base+ \$D6	\$6B	SCI0	I bit SCI0CR2 (TIE, TCIE, RIE, ILIE		
Vector base + \$D4	\$6A	SCI1	l bit	SCI1CR2 (TIE, TCIE, RIE, ILIE)	
Vector base + \$D2	\$69	ATD0	l bit	ATD0CTL2 (ASCIE)	
Vector base + \$D2		Reserved			
Vector base + \$D0	\$68	ATD1	l bit	ATD1CTL2 (ASCIE)	
Vector base + \$CE	\$67	Port J	l bit	PIEJ (PIEJ7-PIEJ0)	
Vector base + \$CC	\$66	Port H	l bit	PIEH (PIEH7-PIEH0)	
Vector base + \$CA	\$65	Modulus down counter underflow	l bit	MCCTL(MCZI)	
Vector base + \$C8	\$64	Pulse accumulator B overflow	l bit	PBCTL(PBOVI)	
Vector base + \$C6	\$63	CRG PLL lock	I bit	CRGINT(LOCKIE)	
Vector base + \$C4	\$62	CRG self-clock mode	l bit	CRGINT (SCMIE)	
Vector base + \$C2		Reserved			
Vector base + \$C0	\$60	IIC0 bus	I bit	IBCR0 (IBIE)	

Fable 1-12. Interrupt Vector Locations (Sheet 1	of 3)	
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	7	6	5	4	3	2	1	0			
R		AFEC	۸\۸/۸۱		ETRICP	ETRICE		ASCIF			
W	ADI U			LINIGEL	LING	LINGE	AGOIL				
Reset	0	0	0	0	0	0	0	0			
	= Unimplemented or Reserved										

Figure 4-5. ATD Control Register 2 (ATDCTL2)

Read: Anytime

Write: Anytime

Field	Description
7 ADPU	 ATD Power Down — This bit provides on/off control over the ATD10B16C block allowing reduced MCU power consumption. Because analog electronic is turned off when powered down, the ATD requires a recovery time period after ADPU bit is enabled. 0 Power down ATD 1 Normal ATD functionality
6 AFFC	 ATD Fast Flag Clear All ATD flag clearing operates normally (read the status register ATDSTAT1 before reading the result register to clear the associate CCF flag). Changes all ATD conversion complete flags to a fast clear sequence. Any access to a result register will cause the associate CCF flag to clear automatically.
5 AWAI	 ATD Power Down in Wait Mode — When entering Wait Mode this bit provides on/off control over the ATD10B16C block allowing reduced MCU power. Because analog electronic is turned off when powered down, the ATD requires a recovery time period after exit from Wait mode. 0 ATD continues to run in Wait mode 1 Halt conversion and power down ATD during Wait mode After exiting Wait mode with an interrupt conversion will resume. But due to the recovery time the result of this conversion should be ignored.
4 ETRIGLE	External Trigger Level/Edge Control — This bit controls the sensitivity of the external trigger signal. See Table 4-7 for details.
3 ETRIGP	External Trigger Polarity — This bit controls the polarity of the external trigger signal. See Table 4-7 for details.
2 ETRIGE	 External Trigger Mode Enable — This bit enables the external trigger on one of the AD channels or one of the ETRIG[3:0] inputs as described in Table 4-5. If external trigger source is one of the AD channels, the digital input buffer of this channel is enabled. The external trigger allows to synchronize the start of conversion with external events. 0 Disable external trigger 1 Enable external trigger
1 ASCIE	 ATD Sequence Complete Interrupt Enable 0 ATD Sequence Complete interrupt requests are disabled. 1 ATD Interrupt will be requested whenever ASCIF = 1 is set.
0 ASCIF	ATD Sequence Complete Interrupt Flag — If ASCIE = 1 the ASCIF flag equals the SCF flag (see Section 4.3.2.7, "ATD Status Register 0 (ATDSTAT0)"), else ASCIF reads zero. Writes have no effect. 0 No ATD interrupt occurred 1 ATD sequence complete interrupt pending



Compare



Operation

 $RS2 - RS1 \implies NONE \text{ (translates to SUB R0, RS1, RS2)}$

 $RD - IMM16 \implies NONE$ (translates to CMPL RD, #IMM16[7:0]; CPCH RD, #IMM16[15:8])

Subtracts two 16 bit values and discards the result.

CCR Effects

Ν	Ζ	V	С
Δ	Δ	Δ	Δ

N: Set if bit 15 of the result is set; cleared otherwise.

- Z: Set if the result is \$0000; cleared otherwise.
- V: Set if a two's complement overflow resulted from the operation; cleared otherwise. RS1[15] & <u>RS2[15]</u> & result[15] | <u>RS1[15]</u> & RS2[15] & result[15] RD[15] & <u>IMM16[15]</u> & result[15] | <u>RD[15]</u> & <u>IMM16[15]</u> & result[15]
- C: Set if there is a carry from the bit 15 of the result; cleared otherwise. RS1[15] & RS2[15] | RS1[15] & result[15] | RS2[15] & result[15] RD[15] & IMM16[15] | RD[15] & result[15] | IMM16[15] & result[15]

Code and CPU Cycles

Source Form	Address Mode		Machine Code									Cycles	
CMP RS1, RS2	TRI	0	0	0	1	1	0 0	0	RS1	RS2	0	0	Р
CMP RS, #IMM16	IMM8	1	1	0	1	0	RS	RS IMM16[7:0]		Р			
	IMM8	1	1	0	1	1	RS		IM	M16[15:8]			Р



6.9 Initialization and Application Information

6.9.1 Initialization

The recommended initialization of the XGATE is as follows:

- 1. Clear the XGE bit to suppress any incoming service requests.
- 2. Make sure that no thread is running on the XGATE. This can be done in several ways:
 - a) Poll the XGCHID register until it reads \$00. Also poll XGDBG and XGSWEIF to make sure that the XGATE has not been stopped.
 - b) Enter Debug Mode by setting the XGDBG bit. Clear the XGCHID register. Clear the XGDBG bit.

The recommended method is a).

- 3. Set the XGVBR register to the lowest address of the XGATE vector space.
- 4. Clear all Channel ID flags.
- 5. Copy XGATE vectors and code into the RAM.
- 6. Initialize the S12X_INT module.
- 7. Enable the XGATE by setting the XGE bit.

The following code example implements the XGATE initialization sequence.

6.9.2 Code Example (Transmit "Hello World!" on SCI)

	CPU	S12X		
	;####	####################	##########################	#
	;#	S	YMBOLS	#
	;####	####################	##########################	#
SCI_REGS	EQU	\$00C8	;SCI register space	
SCIBDH	EQU	SCI_REGS+\$00	;SCI Baud Rate Registe	er
SCIBDL	EQU	SCI_REGS+\$00	;SCI Baud Rate Registe	er
SCICR2	EQU	SCI_REGS+\$03	;SCI Control Register	2
SCISR1	EQU	SCI_REGS+\$04	;SCI Status Register	1
SCIDRL	EQU	SCI_REGS+\$07	;SCI Control Register	2
TIE	EQU	\$80	;TIE bit mask	
TE	EQU	\$08	;TE bit mask	
RE	EQU	\$04	;RE bit mask	
SCI_VEC	EQU	\$D6	;SCI vector number	
			+0100	
INT_REGS		EQU	\$0120 ; S12X_	_IN'I' register space
IN'I'_CF'ADDR	EQU	INT_REGS+\$07	;Interrupt Configurati	on Address Register
INT_CFDATA	EQU	INT_REGS+\$08	;Interrupt Configurati	on Data Registers
RQST	EQU	\$80	;RQST bit mask	
XGATE REGS	EOU	\$0380	:XGATE register space	
XGMCTL	EOU	XGATE REGS+\$00	;XGATE Module Control	Register
XGMCTL_CLEAR	EQU	\$FA02	;Clear all XGMCTL bits	3
XGMCTL_ENABLE	EQU	\$8282	;Enable XGATE	
XGCHID	EQU	XGATE_REGS+\$02	;XGATE Channel ID Regi	ster
XGVBR	EQU	XGATE_REGS+\$06	;XGATE ISP Select Regi	ster
XGIF	EQU	XGATE_REGS+\$08	;XGATE Interrupt Flag	Vector











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The MMCCTL0 register is used to control external bus functions, i.e., availability of chip selects.

CAUTION

XGATE write access to this register during an CPU access which makes use of this register could lead to unexpected results.

Table 17-4. MMCCTL0 Field Descriptions

Field	Description
3–0 CS[3:0]E	Chip Select Enables — Each of these bits enables one of the external chip selects $\overline{CS3}$, $\overline{CS2}$, $\overline{CS1}$, and $\overline{CS0}$ outputs which are asserted during accesses to specific external addresses. The associated global address ranges are shown in Table 1-6 and Table 1-21 and Figure 1-23.
	 Chip selects are only active if enabled in normal expanded mode, Emulation expanded mode and special test mode. The function disabled in all other operating modes. 0 Chip select is disabled 1 Chip select is enabled

Table 17-5. Chip Select Signals

Global Address Range	Asserted Signal
0x00_0800-0x0F_FFFF	CS3
0x10_0000-0x1F_FFFF	CS2
0x20_0000-0x3F_FFFF	CS1
0x40_0000-0x7F_FFFF	CS0 ¹

¹ When the internal NVM is enabled (see ROMON in Section 1.3.2.5, "MMC Control Register (MMCCTL1)") the CSO is not asserted in the space occupied by this on-chip memory block.

I

Field	Description
7–0 PIX[7:0]	Program Page Index Bits 7–0 — These page index bits are used to select which of the 256 FLASH or ROM array pages is to be accessed in the Program Page Window.

Table 18-14. PPAGE Field Descriptions

The fixed 16K page from 0x4000-0x7FFF (when ROMHM = 0) is the page number 0xFD.

The reset value of 0xFE ensures that there is linear Flash space available between addresses 0x4000 and 0xFFFF out of reset.

The fixed 16K page from 0xC000-0xFFFF is the page number 0xFF.

18.3.2.9 RAM Write Protection Control Register (RAMWPC)



Read: Anytime

Write: Anytime

Table 18-15. RAMWPC Field Descriptions

Field	Description
0 RWPE	 RAM Write Protection Enable — This bit enables the RAM write protection mechanism. When the RWPE bit is cleared, there is no write protection and any memory location is writable by the CPU module and the XGATE module. When the RWPE bit is set the write protection mechanism is enabled and write access of the CPU or to the XGATE RAM region. Write access performed by the XGATE module to outside of the XGATE RAM region or the shared region is suppressed as well in this case. 0 RAM write protection check is disabled, region boundary registers can be written. 1 RAM write protection check is enabled, region boundary registers cannot be written.
1 AVIE	 CPU Access Violation Interrupt Enable — This bit enables the Access Violation Interrupt. If AVIE is set and AVIF is set, an interrupt is generated. 0 CPU Access Violation Interrupt Disabled. 1 CPU Access Violation Interrupt Enabled.
0 AVIF	 CPU Access Violation Interrupt Flag — When set, this bit indicates that the CPU has tried to write a memory location inside the XGATE RAM region. This flag can be reset by writing '1' to the AVIF bit location. 0 No access violation by the CPU was detected. 1 Access violation by the CPU was detected.

18 Memory Mapping Control (S12XMMCV3)

Table 18-21 shows the address boundaries of each chip select and the relationship with the implemented resources (internal) parameters.

Chip Selects	Bottom Address	Top Address		
CS3	0x00_0800	0x0F_FFFF minus RAMSIZE ¹		
CS2	0x10_0000	0x13_FFFF minus EEPROMSIZE ²		
CS2 ³	0x14_0000	0x1F_FFF		
CS1	0x20_0000	0x3F_FFF		
$\overline{\text{CS0}}^4$	0x40_0000	0x7F_FFFF minus FLASHSIZE ⁵		

Table 18-21. Global Chip Selects Memory Space

¹ External RPAGE accesses in (NX, EX and ST)

² External EPAGE accesses in (NX, EX and ST)

³ When ROMHM is set (see ROMHM in Table 18-19) the $\overline{CS2}$ is asserted in the space occupied by this on-chip memory block.

⁴ When the internal NVM is enabled (see ROMON in Section 18.3.2.5, "MMC Control Register (MMCCTL1)) the CS0 is not asserted in the space occupied by this on-chip memory block.

⁵ External PPAGE accesses in (NX, EX and ST)

Figure 18-23. Local to Implemented Global Address Mapping (Without GPAGE)

18.4.2.4 XGATE Memory Map Scheme

18.4.2.4.1 Expansion of the XGATE Local Address Map

The XGATE 64 Kbyte memory space allows access to internal resources only (Registers, RAM, and FLASH). The 2 Kilobyte register address range is the same register address range as for the CPU and the BDM module . XGATE can access the FLASH in single chip modes, even when the MCU is secured. In expanded modes, XGATE can not access the FLASH when MCU is secured.

The local address of the XGATE RAM access is translated to the global RAM address range. The XGATE shares the RAM resource with the CPU and the BDM module . The local address of the XGATE FLASH access is translated to the global address as shown in Figure 18-24. For the implemented memory spaces and addresses please refer to Table 1-4 and Table 1-5.





Figure 18-24. XGATE Global Address Mapping

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21 External Bus Interface (S12XEBIV2)

21.4 Functional Description

This section describes the functions of the external bus interface. The availability of external signals and functions in relation to the operating mode is initially summarized and described in more detail in separate sub-sections.

21.4.1 Operating Modes and External Bus Properties

A summary of the external bus interface functions for each operating mode is shown in Table 21-7.

Drepartica	Single-Ch	nip Modes	Expanded Modes							
(if Enabled)	Normal Special Single-Chip Single-Chip		Normal Expanded	Emulation Single-Chip	Emulation Expanded	Special Test				
Timing Properties										
PRR access ¹	2 cycles read internal write internal	2 cycles read internal write internal	2 cycles read internal write internal	2 cycles read external write int & ext	2 cycles read external write int & ext	2 cycles read internal write internal				
Internal access visible externally	—			1 cycle	1 cycle	1 cycle				
External — — address access and unimplemented area access ²		Max. of 2 to 9 1 cycle programmed cycles or n cycles of ext. wait ³		Max. of 2 to 9 programmed cycles or n cycles of ext. wait ³	1 cycle					
Flash area — — — address access ⁴			1 cycle	1 cycle	1 cycle					
		Sign	al Properties							
Bus signals	Bus signals — —		ADDR[22:1] DATA[15:0]	ADDR[22:20]/A CC[2:0] ADDR[19:16]/ IQSTAT[3:0] ADDR[15:0]/ IVD[15:0] DATA[15:0]	ADDR[22:20]/A CC[2:0] ADDR[19:16]/ IQSTAT[3:0] ADDR[15:0]/ IVD[15:0] DATA[15:0]	ADDR[22:0] DATA[15:0]				
Data select signals (if 16-bit data bus)	_	_	UDS LDS	ADDR0 LSTRB	ADDR0 LSTRB	ADDR0 LSTRB				
Data direction signals	—	_	RE WE	R/W	R/W	R/W				
External wait feature			EWAIT	—	EWAIT	—				
Reduced input threshold enabled on	—		Refer to Table 21-3	DATA[15:0] EWAIT	DATA[15:0] EWAIT	Refer to Table 21-3				

	- · -	-			
Table	21-7.	Summary	/ Of	Function	ons

¹ Incl. S12X_EBI registers

² Refer to S12X_MMC section.

³ If EWAITE = 1, the minimum number of external bus cycles is 3.

⁴ Available only if configured appropriately by ROMON and EROMON (refer to S12X_MMC section).







Figure 22-24. Port T Polarity Select Register (PPST)

Read: Anytime.

Write: Anytime.

This register selects whether a pull-down or a pull-up device is connected to the pin.

Table 22-26. PPST Field Descriptions

Field	Description
7–0	Pull Select Port T
PPST[7:0]	 0 A pull-up device is connected to the associated port T pin, if enabled by the associated bit in register PERT and if the port is used as input. 1 A pull-down device is connected to the associated port T pin, if enabled by the associated bit in register PERT and if the port is used as input.

22.3.2.23 Port S Data Register (PTS)

	7	6	5	4	3	2	1	0
R W	PTS7	PTS6	PTS5	PTS4	PTS3	PTS2	PTS1	PTS0
SCI/SPI	SSO	SCK0	MOSI0	MISO0	TXD1	RXD1	TXD0	RXD0
Reset	0	0	0	0	0	0	0	0

Figure 22-25. Port S Data Register (PTS)

Read: Anytime.

Write: Anytime.

Port S pins 7–4 are associated with the SPI0. The SPI0 pin configuration is determined by several status bits in the SPI0 module. *Refer to SPI section for details*. When not used with the SPI0, these pins can be used as general purpose I/O.

Port S bits 3–0 are associated with the SCI1 and SCI0. The SCI ports associated with transmit pins 3 and 1 are configured as outputs if the transmitter is enabled. The SCI ports associated with receive pins 2 and 0 are configured as inputs if the receiver is enabled. *Refer to SCI section for details*. When not used with the SCI, these pins can be used as general purpose I/O.

If the data direction bits of the associated I/O pins are set to logic level "1", a read returns the value of the port register, otherwise the buffered pin input state is read.







Read: Anytime.

Write: Anytime.

This register selects whether a pull-down or a pull-up device is connected to the pin. If CAN is active, a pull-up device can be activated on the related RXCAN inputs, but not a pull-down.

Table 23-36. PPSM Field Descriptions

Field	Description
7–0	Pull Select Port M
PPSM[7:0]	 0 A pull-up device is connected to the associated port M pin, if enabled by the associated bit in register PERM and if the port is used as general purpose or RXCAN input. 1 A pull-down device is connected to the associated port M pin, if enabled by the associated bit in register PERM and if the port is used as a general purpose but not as RXCAN.

23.0.5.36 Port M Wired-OR Mode Register (WOMM)

_	7	6	5	4	3	2	1	0
R W	WOMM7	WOMM6	WOMM5	WOMM4	WOMM3	WOMM2	WOMM1	WOMM0
Reset	0	0	0	0	0	0	0	0

Figure 23-38. Port M Wired-OR Mode Register (WOMM)

Read: Anytime.

Write: Anytime.

This register configures the output pins as wired-OR. If enabled the output is driven active low only (open-drain). A logic level of "1" is not driven. It applies also to the CAN outputs and allows a multipoint connection of several serial modules. This bit has no influence on pins used as inputs.

Table 23-37. WOMM Field Descriptions

Field	Description
7–0	Wired-OR Mode Port M
WOMM[7:0]	0 Output buffers operate as push-pull outputs.
	1 Output buffers operate as open-drain outputs.

Field	Description
3–2 PTM[3:2]	The routed CAN0 function (TXCAN0 and RXCAN0) takes precedence over the routed SPI0 and the general purpose I/O function if the routed CAN0 module is enabled. <i>Refer to MSCAN section for details.</i>
	The routed SPI0 function (SS0 and MISO0) takes precedence of the general purpose I/O function if the routed SPI0 is enabled and not in bidirectional mode. <i>Refer to SPI section for details.</i>
1–0 PTM[1:0]	The CAN0 function (TXCAN0 and RXCAN0) takes precedence over the general purpose I/O function if the CAN0 module is enabled. <i>Refer to MSCAN section for details.</i>

Table 24-28. PTM Field Descriptions (continued)

24.0.5.27 Port M Input Register (PTIM)



Figure 24-29. Port M Input Register (PTIM)

1. These registers are reset to zero. Two bus clock cycles after reset release the register values are updated with the associated pin values.

Read: Anytime.

Write: Never, writes to this register have no effect.

This register always reads back the buffered state of the associated pins. This can also be used to detect overload or short circuit conditions on output pins.

24.0.5.28 Port M Data Direction Register (DDRM)



Figure 24-30. Port M Data Direction Register (DDRM)

Read: Anytime.

Write: Anytime.

This register configures each port M pin as either input or output.

The CAN forces the I/O state to be an output for each port line associated with an enabled output (TXCAN). It also forces the I/O state to be an input for each port line associated with an enabled input (RXCAN). In those cases the data direction bits will not change.



Figure 28-22. RESERVED3

All bits read 0 and are not writable.

28 256 Kbyte Flash Module (S12XFTX256K2V1)

28.3.2.14 RESERVED4

This register is reserved for factory testing and is not accessible.



Figure 28-23. RESERVED4

All bits read 0 and are not writable.

28.4 Functional Description

28.4.1 Flash Command Operations

Write operations are used to execute program, erase, erase verify, erase abort, and data compress algorithms described in this section. The program and erase algorithms are controlled by a state machine whose timebase, FCLK, is derived from the oscillator clock via a programmable divider. The command register, as well as the associated address and data registers, operate as a buffer and a register (2-stage FIFO) so that a second command along with the necessary data and address can be stored to the buffer while the first command is still in progress. This pipelined operation allows a time optimization when programming more than one word on a specific row in the Flash block as the high voltage generation can be kept active in between two programming commands. The pipelined operation allows a simplification of command launching. Buffer empty as well as command completion are signalled by flags in the Flash status register with corresponding interrupts generated, if enabled.

The next sections describe:

- 1. How to write the FCLKDIV register
- 2. Command write sequences to program, erase, erase verify, erase abort, and data compress operations on the Flash memory
- 3. Valid Flash commands
- 4. Effects resulting from illegal Flash command write sequences or aborting Flash operations



[•] 29 128 Kbyte Flash Module (S12XFTX128K1V1)

between the written data and the backdoor key data stored in the Flash memory. If all four words of data are written to the correct addresses in the correct order and the data matches the backdoor keys stored in the Flash memory, the MCU will be unsecured. The data must be written to the backdoor keys sequentially starting with 0x7F_FF00–1 and ending with 0x7F_FF06–7. 0x0000 and 0xFFFF are not permitted as backdoor keys. While the KEYACC bit is set, reads of the Flash memory will return invalid data.

The user code stored in the Flash memory must have a method of receiving the backdoor keys from an external stimulus. This external stimulus would typically be through one of the on-chip serial ports.

If the KEYEN[1:0] bits are in the enabled state (see Section 29.3.2.2, "Flash Security Register (FSEC)"), the MCU can be unsecured by the backdoor key access sequence described below:

- 1. Set the KEYACC bit in the Flash Configuration Register (FCNFG).
- 2. Write the correct four 16-bit words to Flash addresses 0xFF00–0xFF07 sequentially starting with 0x7F_FF00.
- 3. Clear the KEYACC bit. Depending on the user code used to write the backdoor keys, a wait cycle (NOP) may be required before clearing the KEYACC bit.
- 4. If all four 16-bit words match the backdoor keys stored in Flash addresses 0x7F_FF00-0x7F_FF07, the MCU is unsecured and the SEC[1:0] bits in the FSEC register are forced to the unsecure state of 1:0.

The backdoor key access sequence is monitored by an internal security state machine. An illegal operation during the backdoor key access sequence will cause the security state machine to lock, leaving the MCU in the secured state. A reset of the MCU will cause the security state machine to exit the lock state and allow a new backdoor key access sequence to be attempted. The following operations during the backdoor key access sequence will lock the security state machine:

- 1. If any of the four 16-bit words does not match the backdoor keys programmed in the Flash array.
- 2. If the four 16-bit words are written in the wrong sequence.
- 3. If more than four 16-bit words are written.
- 4. If any of the four 16-bit words written are 0x0000 or 0xFFFF.
- 5. If the KEYACC bit does not remain set while the four 16-bit words are written.
- 6. If any two of the four 16-bit words are written on successive MCU clock cycles.

After the backdoor keys have been correctly matched, the MCU will be unsecured. Once the MCU is unsecured, the Flash security byte can be programmed to the unsecure state, if desired.

In the unsecure state, the user has full control of the contents of the backdoor keys by programming addresses $0x7F_F00-0x7F_F07$ in the Flash Configuration Field.

The security as defined in the Flash security byte $(0x7F_FF0F)$ is not changed by using the backdoor key access sequence to unsecure. The backdoor keys stored in addresses $0x7F_FF00-0x7F_FF07$ are unaffected by the backdoor key access sequence. After the next reset of the MCU, the security state of the Flash module is determined by the Flash security byte $(0x7F_FF0F)$. The backdoor key access sequence has no effect on the program and erase protections defined in the Flash protection register.

It is not possible to unsecure the MCU in special single chip mode by using the backdoor key access sequence in background debug mode (BDM).









Device	Package	Flash	RAM	EEPROM	ROM
051220128	112 LQFP	- 128K	8К	2K	
931270128	80 QFP				
9S12XD64	80 QFP	64K	4K	1K	

Table E-1. Memory Sizes and Package Options S12XD-Family